**Product data sheet** 

## 1. General description

Dual common cathode power Schottky diode designed for high frequency switched mode power supplies in a TO220F "full pack" plastic package.





### 2. Features and benefits

- Trench structure
- High junction temperature up to 150 °C
- · Low forward voltage drop, negligible switching losses
- High efficiency

## 3. Applications

- · DC to DC converters
- Freewheeling diode
- OR-ing diode

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit	
Absolute	maximum rating						
$V_{RRM}$	repetitive peak reverse voltage		100		V		
$I_{F(AV)}$	average forward current	$\delta$ = 0.5; square-wave pulse; per diode; Fig. 1; Fig. 2; Fig. 3	10		А		
I <sub>O(AV)</sub>	average output current	$\delta$ = 0.5 ; square-wave pulse; both diodes conducting	20		А		
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static ch	aracteristics						
$V_{F}$	forward voltage	I <sub>F</sub> = 5 A; T <sub>j</sub> = 25 °C; per diode; <u>Fig. 6</u>		-	0.54	0.62	V
		I <sub>F</sub> = 5 A; T <sub>j</sub> = 125 °C; per diode; <u>Fig. 6</u>		-	0.51	0.58	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; per diode; <u>Fig. 6</u>		-	0.68	0.75	V
		$I_F = 10 \text{ A}; T_j = 125 ^{\circ}\text{C}; \text{ per diode}; Fig. 6$		-	0.63	0.7	V
I <sub>R</sub>	reverse current	$V_R = 100 \text{ V}; T_j = 25 \text{ °C}; \text{ per diode}; Fig. 7; Fig. 8$		-	-	50	μΑ
		$V_R = 100 \text{ V}; T_j = 125 ^{\circ}\text{C}; \text{ per diode}; $ Fig. 7; Fig. 8		-	-	15	mA

# 5. Pinning information

**Table 2. Pinning information** 

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode 1	mb	
2	K	cathode		A1 A2
3	A2	anode 2		K sym125
mb	n.c.	mounting base; isolated		Symres

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WN3S20H100CX	TO220F	WN3S20H100CXQ	Tube	50	SOT186A	14-Nov-2013

## 7. Marking

### **Table 4. Marking codes**

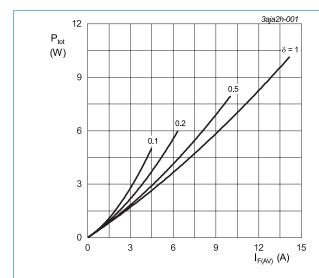
Type number	Marking codes
WN3S20H100CX	WN3S 20H100CX

## 8. Limiting values

#### Table 5. Limiting values

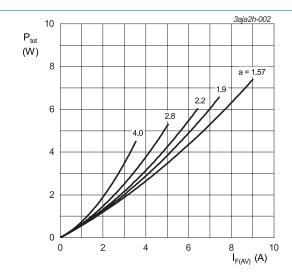
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		100	V
$V_{\text{RWM}}$	crest working reverse voltage		100	V
$V_R$	reverse voltage	DC	100	V
$I_{F(AV)}$	average forward current	$\delta$ = 0.5 ; square-wave pulse; per diode; Fig. 1; Fig. 2; Fig. 3	10	А
$I_{O(AV)}$	average output current	$\delta$ = 0.5 ; square-wave pulse; both diodes conducting	20	Α
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode; Fig. 4	180	А
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; per diode	198	Α
T <sub>stg</sub>	storage temperature		-40 to 150	°C
T <sub>j</sub>	junction temperature		150	°C



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$  $V_o = 0.531 \text{ V; } R_s = 0.0131 \text{ }Ω$ 

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values; per diode



a = form factor =  $I_{F(RMS)}$  /  $I_{F(AV)}$ V<sub>o</sub> = 0.531 V; R<sub>s</sub> = 0.0131  $\Omega$ 

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values; per diode

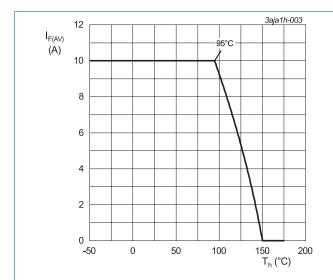


Fig. 3. Average forward current as a function of heatsink temperature; maximum values; per diode

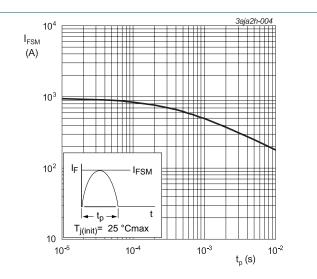


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values; per diode

### 9. Thermal characteristics

#### **Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-h)</sub>	thermal resistance from junction to	with heatsink compound; per diode; Fig. 5	-	-	7	K/W
	heatsink	with heatsink compound; both diodes conducting	-	-	4.8	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient free air	in free air	-	65	-	K/W

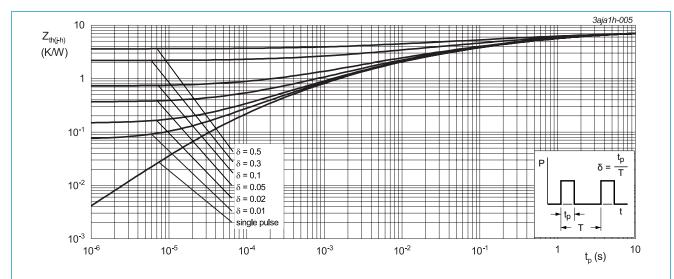


Fig. 5. Transient thermal impedance from junction to heatsink as a function of pulse duration; maximum values; per diode

### 10. Isolation characteristics

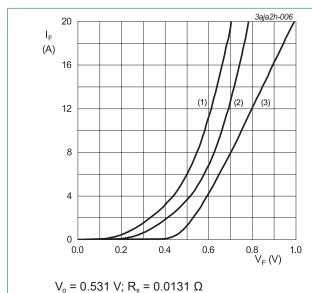
#### **Table 7. Isolation characteristics**

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>isol(RMS)</sub>	RMS isolation voltage	from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz $\leq$ f $\leq$ 60 Hz; T <sub>h</sub> = 25 °C; RH $\leq$ 65 %	-	-	2500	V

### 11. Characteristics

**Table 8. Characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static characteristics							
V <sub>F</sub> forward voltage		$I_F = 5 \text{ A}$ ; $T_j = 25 \text{ °C}$ ; per diode; Fig. 6		-	0.54	0.62	V
		I <sub>F</sub> = 5 A; T <sub>j</sub> = 125 °C; per diode; <u>Fig. 6</u>		-	0.51	0.58	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 25 °C; per diode; <u>Fig. 6</u>		-	0.68	0.75	V
		I <sub>F</sub> = 10 A; T <sub>j</sub> = 125 °C; per diode; <u>Fig. 6</u>		-	0.63	0.7	V
I <sub>R</sub>	reverse current	$V_R = 100 \text{ V}; T_j = 25 \text{ °C}; \text{ per diode}; $ Fig. 7; Fig. 8		-	-	50	μΑ
		$V_R = 100 \text{ V}; T_j = 125 \text{ °C}; \text{ per diode}; $ Fig. 7; Fig. 8		-	-	15	mA



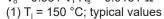
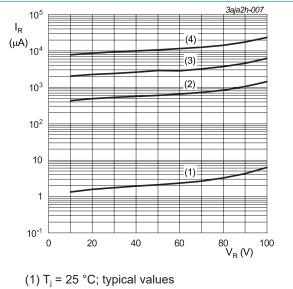


Fig. 6. Forward current as a function of forward voltage; per diode



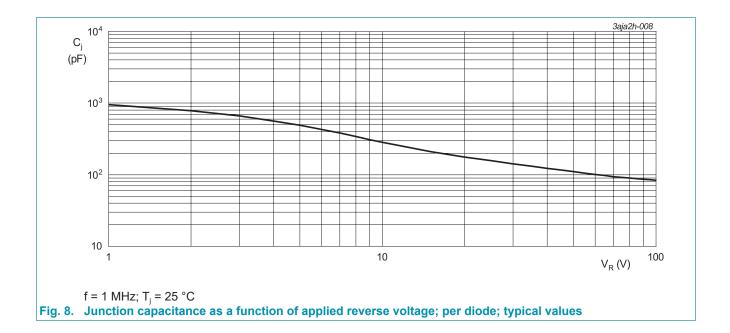
<sup>(2)</sup> T<sub>i</sub> = 100 °C; typical values

Fig. 7. Reverse leakage current as a function of reverse voltage; per diode; typical values

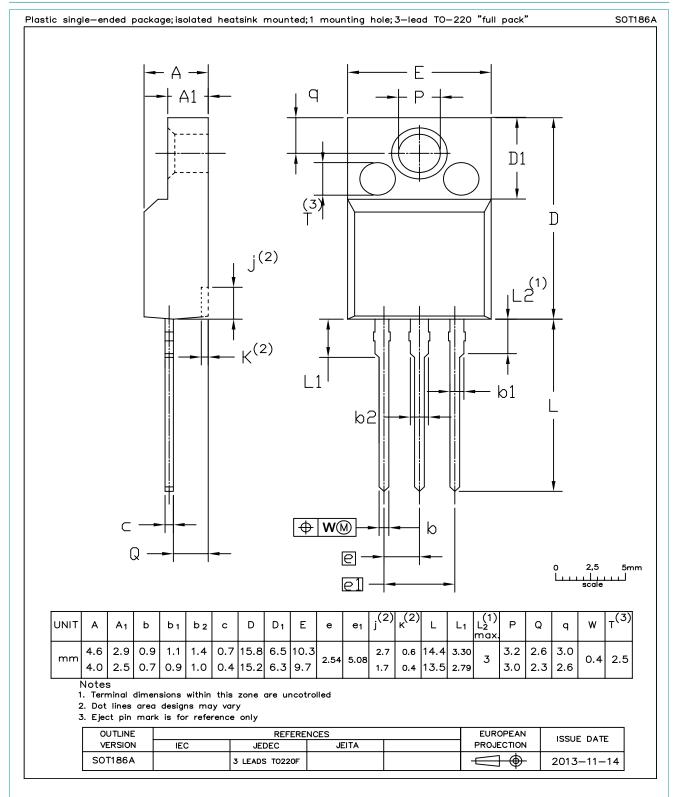
<sup>(2)</sup> T<sub>i</sub> = 150 °C; maximum values

<sup>(3)</sup>  $T_i = 25$  °C; maximum values

<sup>(3)</sup>  $T_j = 125$  °C; typical values (4)  $T_j = 150$  °C; typical values



## 12. Package outline



## 13. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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